

### OSI5120421E

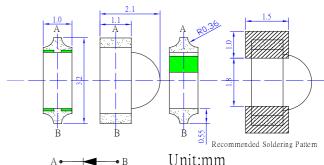
#### **■Features**

- · Single chip
- Compact package outline
   (L x W x T) of 3.2mm x 1.0mm x2.1mm
- · Compatible to IR reflow soldering.
- · Water Clear Lens Type

### **■**Applications

- · Automatic Control System
- · Photo Detector
- Computer I/O Peripheral

#### **■Outline Dimension**



A:Cathode B:Anode

(Ta=25°C)

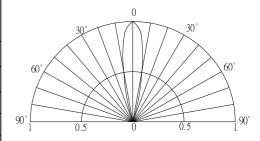
(Ta=25°C)

Unit:mm Tolerance:±0.20mm unless otherwise noted

### ■Absolute Maximum Rating

Item	Symbol	Value	Unit
DC Forward Current	$I_{\mathrm{F}}$	100	mA
Pulse Forward Current#	$I_{\mathrm{FP}}$	300	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation	$P_D$	130	mW
Operating Temperature	Topr	-30 ~ +85	$^{\circ}\! C$
Storage Temperature	Tstg	-40~ +100	$^{\circ}\!\mathbb{C}$
Lead Soldering Temperature	Tsol	260°€/5sec	=-

# **■**Directivity



### **■ Electrical -Optical Characteristics**

			,			
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
DC Forward Voltage	$V_{F}$	I <sub>F</sub> =5mA	1	1.2	1.3	V
DC Reverse Current	$I_R$	V <sub>R</sub> =5V	1	1	10	μΑ
Peak Wavelength	$\lambda_{\mathrm{p}}$	I <sub>F</sub> =5mA	1	940	1	nm
Transmit Bandwidth	λ	I <sub>F</sub> =5mA	35	45	55	nm
Radiant Intensity	Ie	I <sub>F</sub> =5mA	1	5	-	mW/Sr
50% Power Angle	2θ1/2	I <sub>F</sub> =5mA	-	20	-	deg

<sup>\*1</sup> Tolerance of measurements of Peak wavelength is ±1nm









<sup>#</sup>Pulse width Max 0.1ms, Duty ratio max 1/10

<sup>\*2</sup> Tolerance of measurements of radiant intensity is ±15%

<sup>\*3</sup> Tolerance of measurements of forward voltage is ±0.1V

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# **■**Typical Electrical/Optical/Characteristics Curves

Fig.1 Forward Current vsAmbient Temperature

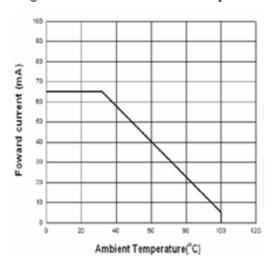


Fig.3 Relative Intensity vs. Forward Current

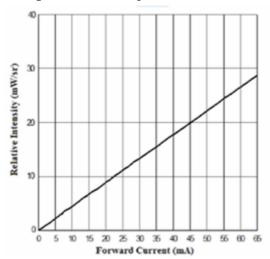


Fig.2 Spectral Sensitivity↔

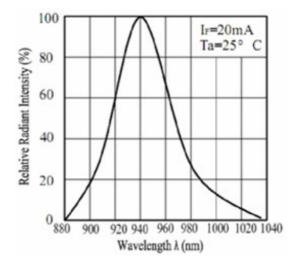
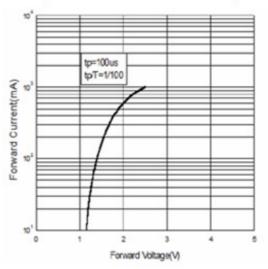


Fig.4 Forward Current vs. Forward Voltage











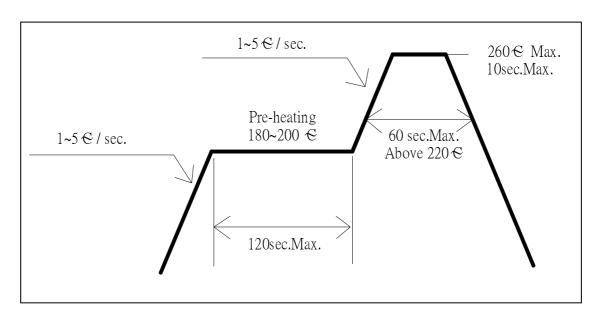


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# **■ Soldering Conditions**

Reflow Soldering		Hand Soldering		
Pre-Heat	180 ~ 200°C			
Pre-Heat Time	120 sec. Max.		350°C Max. 3 sec. Max.	
Peak temperature	260°C Max.	Temperature Soldering time		
Dipping Time	10 sec. Max.			
Condition	Refer to Temperature-profile		(one time only)	

#### • Reflow Soldering Condition(Lead-free Solder)



- \*Recommended soldering conditions vary according to the type of LED
- \*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- \*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.











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#### **■ Cautions:**

- 1. After open the package, the LED's floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.







